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(54) Title: SULFOXIDE/GLYCOL ETHER BASED SOLVENTS FOR USE IN THE ELECTRONICS INDUSTRY

(57) Abstract: Solvents useful for removing, among other things, photoresists and poly(amic acid)/polyimide from display/semicon-
ductor substrates or electronic processing equipment, consist essentially of: (A) a first component consisting of a sulfoxide, e.g., DMSO;
(B) a second component consisting of a glycol ether, e.g., ethylene glycol monobutyl ether; and (C) a third component consisting of at
least one of N-formyl morpholine, N, N-dimethyl propionamide, 3-methoxy-N, N-dimethyl propanamide, and triethyl phosphate.

SULFOXIDE/GLYCOL ETHER BASED SOLVENTS FOR USE IN THE ELECTRONICS INDUSTRY

FIELD

[0001] This invention relates to ecology-friendly solvents (“eco-solvents”) useful in the manufacture of various electronic components, e.g., display units and semiconductors.

BACKGROUND

[0002] Some polar solvents, e.g., N-methyl-2-pyrrolidone (NMP), dimethyl acetamide (DMAc), dimethyl formamide (DMF), etc., have reproductive toxicity, which drive the ever increasing global safety and regulatory concerns related to these materials. For example, NMP is listed in the Substance of Very High Concerns (SVHC) registry of the European Globally Harmonized System of Classification and Labeling of Chemicals (GHS) and REACH Annex XVII which lists the restrictions on the manufacture, placing on the market and use of certain dangerous substances, mixtures and articles.

[0003] NMP is used in the electronics industry for cleaning and stripping of various parts (e.g., components for display units, semiconductor substrates, etc.) and equipment, and considerable amounts of it are consumed annually. Developing an eco-solvent to achieve similar performance with a better environmental profile than NMP is an urgent request from electronic processing customers. This invention details solvent combinations that, in some embodiments, provide the same or better cleaning ability, and stripping ability for photoresist removal, than NMP.

SUMMARY

[0004] In one embodiment the invention is a solvent consisting essentially of:

and

- (A) a first component consisting of a sulfoxide;
- (B) a second component consisting of a glycol ether; and
- (C) a third component consisting of at least one of N-formyl morpholine, N,N-dimethyl propionamide, 3-methoxy-N,N-dimethyl propanamide, and triethyl phosphate.

[0005] In one embodiment the invention is a process for cleaning or stripping the surface of a substrate, the process comprising the step of contacting the substrate with a solvent consisting essentially of:

- (A) a first component consisting of a sulfoxide;
- (B) a second component consisting of a glycol ether; and
- (C) a third component consisting of at least one of N-formyl morpholine, N,N-dimethyl propionamide, 3-methoxy-N,N-dimethyl propanamide, and triethyl phosphate.

DETAILED DESCRIPTION

Definitions

[0006] For purposes of United States patent practice, the contents of any referenced patent, patent application or publication are incorporated by reference in their entirety (or its equivalent U.S. version is so incorporated by reference) especially with respect to the disclosure of definitions (to the extent not inconsistent with any definitions specifically provided in this disclosure) and general knowledge in the art.

[0007] The numerical ranges disclosed herein include all values from, and including, the lower and upper value. For ranges containing explicit values (e.g., 1 to 7), any subrange between any two explicit values is included (e.g., 1 to 2; 2 to 6; 5 to 7; 3 to 7; 5 to 6; etc.).

[0008] The terms "comprising," "including," "having," and their derivatives, are not intended to exclude the presence of any additional component, step or procedure, whether or not the same is specifically disclosed. In order to avoid any doubt, all compositions claimed through use of the term "comprising" may include any additional additive, adjuvant, or compound, whether polymeric or otherwise, unless stated to the contrary. In contrast, the term, "consisting essentially of" excludes from the scope of any succeeding recitation any other component, step, or procedure, excepting those that are not essential to operability. The term "consisting of" excludes any component, step, or procedure not specifically delineated or listed. The term "or," unless stated otherwise, refers to the listed members individually as well as in any combination. Use of the singular includes use of the plural and vice versa.

[0009] Unless stated to the contrary, implicit from the context, or customary in the art, all parts and percents are based on weight and all test methods are current as of the filing date of this disclosure.

[0010] "Solvent" and like terms mean a substance that is capable of dissolving another substance (i.e., a solute) to form an essentially uniformly dispersed mixture (i.e., solution) at the molecular or ionic size level.

[0011] "Electronic part" and like terms mean an in-process or finished product, or component of a product, of a manufacturing process for electronic goods, such as a semiconductor or display unit. Electronic part, as used in the context of this invention, includes the equipment used to manufacture the product.

[0012] "In-process product" and like terms mean an unfinished or intermediate product. In-process products include starting materials, e.g., materials as received from vendors, or materials before subjected to the start of the manufacturing process.

[0013] "Photoresist" and like terms mean a photosensitive resin that loses its resistance to chemical etching when exposed to radiation and is used especially in the transference of a circuit pattern to a semiconductor chip during the production of an integrated circuit.

[0014] "Cleaning" and like terms mean, in the context of this invention, the removal of particulate contamination and metal ions from the surface of a substrate, usually from the surface of an in-process electronic part to ready the part for subsequent processing.

[0015] "Stripping" and like terms mean, in the context of this invention, the removal of a layer, e.g., coating or film, from the surface of a substrate, such as the removal of a photoresist from the surface of a semiconductor substrate.

[0016] Poly(amic acid) is an intermediate polymer in the synthesis of polyimide. It is soluble in polar solvents due to strong hydrogen bonding.

[0017] Polyimide (PI) is a polymer of imide monomers. It is normally produced by the reaction of a dianhydride and a diamine. One common PI used in the electronics industry is KAPTONTM. It is produced from the condensation of pyromellitic dianhydride and 4,4'-oxydiphenylamine.

Solvents

[0018] The solvents of this invention consist essentially of a first component, a second component, and a third component. The first component consists of, or is, a sulfoxide. The second component consists of, or is, a glycol ether. The third component consists of, or consists essentially of, at least one of N-formyl morpholine (CAS Number 4394-85-8), N,N-dimethyl propionamide (CAS Number 758-96-3), 3-methoxy-N,N-dimethyl propanamide

(CAS Number 53185-52-7), and triethyl phosphate (CAS Number 78-40-0). The first, second and third components form a blend, and the blend may or may not be phase separated.

Sulfoxides

[0019] The first component of the solvent of this invention consists of, or is, a sulfoxide, i.e., a compound containing a sulfinyl functional group attached to two carbon atoms. It is a polar functional group. Sulfoxides are the oxidized derivatives of sulfides. Representative sulfoxides include, but are not limited to, diethyl sulfoxide, butyl sulfoxide, tetramethylene sulfoxide and dimethyl sulfoxide (DMSO). The first component can consist of one or more sulfoxides. In one embodiment the first component consists of one sulfoxide. In one embodiment the first component consists of two or more sulfoxides. In one embodiment the first component consists of, or is, DMSO (CAS Number 67-68-5).

Glycol Ethers

[0020] The second component of the solvent of this invention consists of, or is, a glycol ether, i.e., a compound based on an alkyl ether of ethylene glycol or propylene glycol. These solvents typically have a higher boiling point, together with the favorable solvent properties of lower-molecular weight ethers and alcohols. Representative glycol ethers include, but are not limited to, ethylene glycol monobutyl ether, ethylene glycol monopropyl ether, diethylene glycol monoethyl ether, propylene glycol monomethyl ether, dipropylene glycol monomethyl ether, and tripropylene glycol monomethyl ether. The second component can consist of one or more glycol ethers. In one embodiment the second component consists of one glycol ether. In one embodiment the second component consists of two or more glycol ethers. In one embodiment the second component is an ethylene glycol alkyl ether. In one embodiment the second component is a propylene glycol alkyl ether. In one embodiment the alkyl component of the ethylene or propylene glycol ether is an alkyl group of 2 to 12, or 3 to 10, or 3 to 8, carbon atoms. In one embodiment the second component consists of, or is, ethylene glycol monobutyl ether (CAS Number 111-76-2).

Embodiments

[0021] In one embodiment the solvent is a blend consisting of, or consisting essentially of, a sulfoxide as the first component, a glycol ether as the second component, and N-formyl morpholine as the third component.

[0022] In one embodiment the solvent is a blend consisting of, or consisting essentially of, a sulfoxide as the first component, a glycol ether as the second component, and N,N-dimethyl propionamide as the third component.

[0023] In one embodiment the solvent is a blend consisting of, or consisting essentially of, a sulfoxide as the first component, a glycol ether as the second component, and 3-methoxy-N,N-dimethyl propanamide as the third component.

[0024] In one embodiment the solvent is a blend consisting of, or consisting essentially of, a sulfoxide as the first component, a glycol ether as the second component, and triethyl phosphate as the third component.

[0025] In one embodiment the solvent is a blend consisting of, or consisting essentially of, DMSO as the first component, a glycol ether as the second component, and N-formyl morpholine as the third component.

[0026] In one embodiment the solvent is a blend consisting of, or consisting essentially of, DMSO as the first component, a glycol ether as the second component, and N,N-dimethyl propionamide as the third component.

[0027] In one embodiment the solvent is a blend consisting of, or consisting essentially of, DMSO as the first component, a glycol ether as the second component, and 3-methoxy-N,N-dimethyl propanamide as the third component.

[0028] In one embodiment the solvent is a blend consisting of, or consisting essentially of, DMSO as the first component, a glycol ether as the second component, and triethyl phosphate as the third component.

[0029] In one embodiment the solvent is a blend consisting of, or consisting essentially of, a sulfoxide as the first component, ethylene glycol monobutyl ether as the second component, and N-formyl morpholine as the third component.

[0030] In one embodiment the solvent is a blend consisting of, or consisting essentially of, a sulfoxide as the first component, ethylene glycol monobutyl ether as the second component, and N,N-dimethyl propionamide as the third component.

[0031] In one embodiment the solvent is a blend consisting of, or consisting essentially of, a sulfoxide as the first component, ethylene glycol monobutyl ether as the second component, and 3-methoxy-N,N-dimethyl propanamide as the third component.

[0032] In one embodiment the solvent is a blend consisting of, or consisting essentially of, a sulfoxide as the first component, ethylene glycol monobutyl ether as the second component, and triethyl phosphate as the third component.

[0033] In one embodiment the solvent is a tertiary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and N-formyl morpholine as the third component.

[0034] In one embodiment the solvent is a tertiary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and N,N-dimethyl propionamide as the third component.

[0035] In one embodiment the solvent is a tertiary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and 3-methoxy-N,N-dimethyl propanamide as the third component.

[0036] In one embodiment the solvent is a tertiary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and triethyl phosphate as the third component.

[0037] In one embodiment the solvent is a quaternary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and a combination of N-formyl morpholine and N,N-dimethyl propionamide as the third component.

[0038] In one embodiment the solvent is a quaternary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and a combination of N-formyl morpholine and 3-methoxy-N,N-dimethyl propanamide as the third component.

[0039] In one embodiment the solvent is a quaternary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and a combination of N-formyl morpholine and triethyl phosphate as the third component.

[0040] In one embodiment the solvent is a quaternary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and a combination of N,N-dimethyl propionamide and 3-methoxy-N,N-dimethyl propanamide as the third component.

[0041] In one embodiment the solvent is a quaternary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and a combination of N,N-dimethyl propionamide and triethyl phosphate as the third component.

[0042] In one embodiment the solvent is a quinary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and a combination of N-formyl morpholine, N,N-dimethyl propionamide and 3-methoxy-N,N-dimethyl propanamide as the third component.

[0043] In one embodiment the solvent is a quinary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and a combination of N-formyl morpholine, N,N-dimethyl propionamide and triethyl phosphate as the third component.

[0044] In one embodiment the solvent is a quinary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and a combination of N,N-dimethyl propionamide, 3-methoxy-N,N-dimethyl propanamide and triethyl phosphate as the third component.

[0045] In one embodiment the solvent is a senary blend consisting of, or consisting essentially of, DMSO as the first component, ethylene glycol monobutyl ether as the second component, and a combination of N-formyl morpholine, N,N-dimethyl propionamide, 3-methoxy-N,N-dimethyl propanamide and triethyl phosphate as the third component.

[0046] In one embodiment the solvent consists of, or consists essentially of, in weight percent (wt%) based on the weight of the solvent, from 50 to 90 wt% of the first component, from 9 to 40 wt% of the second component, and from 1 to 30 wt% of the third component.

[0047] In one embodiment the solvent consists of, or consists essentially of, in weight percent (wt%) based on the weight of the solvent, from 50 to 90 wt% of DMSO, from 9 to 40 wt% of ethylene glycol monobutyl ether, and from 1 to 30 wt% of at least one of N-formyl morpholine, N,N-dimethyl propionamide, 3-methoxy-N,N-dimethyl propanamide and triethyl phosphate as the third component.

[0048] In those embodiments in which the third component consists of more than one substance, e.g., the third component consists essentially of N-formyl morpholine and N,N-dimethyl propionamide and/or 3-methoxy-N,N-dimethyl propanamide and/or triethyl

phosphate, the amount of each compound in the third component can vary widely and to convenience. The amount of each individual substance in the third component can vary from 0 to 100 wt%, or from 1 to 99 wt%, or from 10 to 90 wt%, or from 20 to 80 wt% or from 30 to 70 wt%, or from 40 to 60 wt%, or 50 wt%, based on the weight of the component.

[0049] Optional materials that are not essential to the operability of, but can be included in, the solvents of this invention include, but are not limited to, antioxidants, colorants, water scavengers, stabilizers, and the like. These materials do not have any material impact on the efficacy of the solvent for cleaning or stripping electronic parts. These optional materials are used in known amounts, e.g., 0.10 to 5, or 4, or 3, or 2, or 1, weight percent based on the weight of the solvent, and they are used in known ways.

Preparation of the Solvent

[0050] The solvents of this invention are made using known equipment and known techniques. The individual components of the solvent are commercially available, liquid at ambient conditions (23°C and atmospheric pressure), and can simply be mixed with one another using conventional mixing equipment and standard blending protocols. The components can be added to one another in any order including simultaneously.

Use of the Solvents

[0051] The solvents of this invention are eco-solvents, i.e., they do not have, or have at a reduced level, the toxicology issues associated with NMP. These solvents are useful for cleaning and/or stripping the surfaces of substrates of contaminants and other unwanted substances, particularly polar contaminants and polar unwanted substances.

[0052] In one embodiment the solvents of this invention are intended as a replacement for NMP and other polar solvents used in the electronics industry. As such, they are used in the same manner as NMP and the other polar solvents in such operations as cleaning and stripping of electronic parts and equipment, and the removal of photoresists from various substrates, e.g., semiconductor substrates, and the removal of polyamic acid polymer residue from polyimide coating equipment, e.g., alignment layer and flexible display substrate coating machine. Typically, these methods or processes include the step of contacting the object or substrate to be cleaned or stripped, or from which a photoresist or a polyamic acid/polyimide residue is to be removed, with the solvent under any of various conditions, e.g., ambient conditions, or at an elevated temperature, with or without flow or agitation, e.g.,

printing, spinning, immersing, flushing, vibrating, showering, spraying, etc., for a sufficient period of time to dissolve whatever material, e.g., a contaminant such as poly(amic acid)/polyimide residue, dianhydride, diamine, etc.; a photoresist, and the like, that is to be removed. This contacting step is then typically followed by rinse (one or more, typically with an aqueous liquid such as deionized water) and drying steps.

[0053] The following examples are nonlimiting illustrations of the invention.

EXAMPLES

Materials

[0054] Poly(amic acid), precursor of polyimide: poly (pyromellitic dianhydride-co-4,4'-oxydianiline), amic acid (from Sigma-Aldrich, 15~16 wt% dissolved in NMP).

[0055] Photoresist: SFP-1400 (from Merck).

[0056] Solvents: N-formyl morpholine (from Accela ChemBio, 98%), dimethyl sulfoxide (DMSO), triethyl phosphate (from Sinopharm, 99%), 3-methoxy-N,N-dimethyl propanamide (from BOC Science, 98%), N,N-dimethyl propionamide (from Energy Chemical, 98%), and ethylene glycol monobutyl ether (from The Dow Chemical Company, 99%).

Solvents

[0057] The solvents are designed according to Hansen Solubility Parameter of NMP, DMF, 3-methoxy-N,N-dimethyl propanamide, etc. These commercialized solvents have strong dissolution ability for most electronic materials. The solvents are described in Table 1.

Table 1

Solvents

Example	Component A	Weight %	Component B	Weight %	Component C	Weight %
1	dimethyl sulfoxide	64	ethylene glycol monobutyl ether	30	N-formyl morpholine	6
2	dimethyl sulfoxide	58	ethylene glycol monobutyl ether	30	N-formyl morpholine	12
3	dimethyl sulfoxide	52	ethylene glycol monobutyl ether	30	N-formyl morpholine	18
4	dimethyl sulfoxide	65	ethylene glycol monobutyl ether	28	N,N-dimethyl propionamide	7
5	dimethyl sulfoxide	65	ethylene glycol monobutyl ether	20	N,N-dimethyl propionamide	15
6	dimethyl sulfoxide	66	ethylene glycol monobutyl ether	25	3-methoxy-N,N-dimethyl propanamide	7
7	dimethyl sulfoxide	60	ethylene glycol monobutyl ether	25	3-methoxy-N,N-dimethyl propanamide	15
8	dimethyl sulfoxide	65	ethylene glycol monobutyl ether	29	triethyl phosphate	6
9	dimethyl sulfoxide	65	ethylene glycol monobutyl ether	23	triethyl phosphate	12
10	dimethyl sulfoxide	65	ethylene glycol monobutyl ether	17	triethyl phosphate	18

Table 1 (Cont'd)

Comparative Example	Component A	Weight %	Component B	Weight %	Component C	Weight %
1	N-methyl-2-pyrrolidone	100				
2	3-methoxy-N,N-dimethyl propanamide	100				
3	monoethanolamine	15	diethylene glycol butyl ether	20	DI water	65
4	monoethanolamine	30	diethylene glycol butyl ether	70		
5	monoethanolamine	10	N-methyl-2-pyrrolidone	70	DI water	20

Protocols

[0058] Poly(amic acid) dissolution: A solution of poly (pyromellitic dianhydride-co-4,4'-oxydianiline), amic acid precursor in NMP is contacted with deionized (DI) water or other NMP-insoluble liquid to extract the precursor from the NMP. The poly(amic acid) precursor is then baked at 54°C for 4 hours to evaporate any residual solvent/liquid before it is dissolved by contact with the test solvent. Results are recorded after 12 hours at 54°C.

[0059] Photoresist stripping: Place 2 milliliters (ml) SFP-1400 photoresist solution onto the surface of glass substrate with a size of 100 millimeters (mm) × 100 mm × 1 mm. The substrate is spun with a rotation speed of 500 revolutions per minute (rpm) for 10 seconds (s) to spread out the photoresist solution. The rotation speed is then accelerated to 1000 rpm for 30 s to coat the photoresist homogenously and spin out redundant solvent. The coated substrate is heated to evaporate solvent at 130°C for 10 minutes (min). The stripping step prepares 30 grams (g) example in the container. The baked substrate is placed into the container with shaking, and finally the time is measured for completely removing photoresist from the substrate.

Results

[0060] Poly(amic acid) dissolution: The poly (pyromellitic dianhydride-co-4,4'-oxydianiline), amic acid solubility results of each product are reported in Table 2. The

content of polymer in each example and comparative sample is 20% by weight. The performance is judged through the fluidity of the solution. The two examples, N-formyl morpholine/N,N-dimethyl propionamide, and dimethyl sulfoxide/ N,N-dimethyl propionamide exhibit good fluidity with low viscosity. N-formyl morpholine/ 3-methoxy-N,N-dimethyl propanamide shows a certain fluidity and suitable viscosity. However, in comparative samples, 3-methoxy-N,N-dimethyl propanamide, gels occur in the solutions, which represents the oversaturation of polymer. For N-methyl-2-pyrrolidone, although the sample is able to flow, its viscosity is comparatively high. In general, the solubility of poly (pyromellitic dianhydride-co-4,4'-oxydianiline), amic acid in N-methyl-2-pyrrolidone should be 15% by weight for commercial products. For 3-methoxy-N,N-dimethyl propanamide, the related solubility is comparatively lower. Therefore, the solvency for poly(amic acid) of examples is better than comparative samples.

Table 2

Poly(amic acid) (poly (pyromellitic dianhydride-co-4,4'-oxydianiline), amic acid) Solvency
Performance of Solvents

Example						
Component A	Weight %	Component B	Weight %	Component C	Weight %	Performance
dimethyl sulfoxide	64	ethylene glycol monobutyl ether	30	N-formyl morpholine	6	○
dimethyl sulfoxide	58	ethylene glycol monobutyl ether	30	N-formyl morpholine	12	○
dimethyl sulfoxide	52	ethylene glycol monobutyl ether	30	N-formyl morpholine	18	○
dimethyl sulfoxide	65	ethylene glycol monobutyl ether	28	N,N-dimethyl propionamide	7	○
dimethyl sulfoxide	65	ethylene glycol monobutyl ether	20	N,N-dimethyl propionamide	15	○
dimethyl sulfoxide	66	ethylene glycol monobutyl ether	25	3-methoxy-N,N-dimethyl propanamide	7	○
dimethyl sulfoxide	60	ethylene glycol monobutyl ether	25	3-methoxy-N,N-dimethyl propanamide	15	○
dimethyl sulfoxide	65	ethylene glycol monobutyl ether	29	triethyl phosphate	6	○
dimethyl sulfoxide	65	ethylene glycol monobutyl ether	23	triethyl phosphate	12	○
dimethyl sulfoxide	65	ethylene glycol monobutyl ether	17	triethyl phosphate	18	○

Open circle = fluidity; X = high viscosity (no flow)

Table 2 (Cont'd)

Comparative		
Component	Weight %	Performance
N-methyl-2-pyrrolidone	100	○
3-methoxy-N,N-dimethyl propanamide	100	×

Open circle = fluidity; X = high viscosity (no flow)

[0061] Photoresist stripping: The photoresist stripping results of each combination are listed in Table 3. The performance is evaluated by stripping time. The example, dimethyl sulfoxide/ethylene glycol monobutyl ether/N,N-dimethyl propionamide can completely strip the coated photoresist from the glass substrate within 15 seconds. The other invented dimethyl sulfoxide/ethylene glycol monobutyl ether based examples require 15 to 20 seconds to strip the photoresist. Water based monoethanolamine/diethylene glycol butyl ether and monoethanolamine/N-methyl-2-pyrrolidone comparative samples Dongji (KR1403516B1) need almost a half-minute for stripping. However the other commercial combination, monoethanolamine/diethylene glycol butyl ether without water content shows relatively slow stripping speed. Therefore, the examples possess better stripping performance on SFP-1400 photoresist.

Table 3
Photoresist (SFP-1400) Stripping Performance of Solvents

Example						
Component A	Weight %	Component B	Weight %	Component C	Weight %	Performance
dimethyl sulfoxide	64	ethylene glycol monobutyl ether	30	N-formyl morpholine	6	○
dimethyl sulfoxide	58	ethylene glycol monobutyl ether	30	N-formyl morpholine	12	○
dimethyl sulfoxide	52	ethylene glycol monobutyl ether	30	N-formyl morpholine	18	○
dimethyl sulfoxide	65	ethylene glycol monobutyl ether	28	N,N-dimethyl propionamide	7	⊙
dimethyl sulfoxide	65	ethylene glycol monobutyl ether	20	N,N-dimethyl propionamide	15	⊙
dimethyl sulfoxide	66	ethylene glycol monobutyl ether	25	3-methoxy-N,N-dimethyl propanamide	7	○
dimethyl sulfoxide	60	ethylene glycol monobutyl ether	25	3-methoxy-N,N-dimethyl propanamide	15	○
dimethyl sulfoxide	65	ethylene glycol monobutyl ether	29	triethyl phosphate	6	○
dimethyl sulfoxide	65	ethylene glycol monobutyl ether	23	triethyl phosphate	12	○
dimethyl sulfoxide	65	ethylene glycol monobutyl ether	17	triethyl phosphate	18	○

Circle with a dot = less than (<) 15 seconds; Open circle (i.e., circle without dot) = 15-20 seconds; Triangle – 20-30 seconds; and X = greater than or equal to (≥) 30 seconds.

Table 3 (Cont'd)

Comparative						
Component A	Weight %	Component B	Weight %	Component C	Weight %	Performance
monoethanolamine	15	diethylene glycol butyl ether	20	DI water	65	Δ
monoethanolamine	30	diethylene glycol butyl ether	70			×
monoethanolamine	10	N-methyl-2-pyrrolidone	70	DI water	20	Δ

Circle with a dot = less than (<) 15 seconds; Open circle (i.e., circle without dot) = 15-20 seconds; Triangle – 20-30 seconds; and X = greater than or equal to (≥) 30 seconds.

CLAIMS

1. A solvent consisting essentially of:
 - (A) a first component consisting of a sulfoxide;
 - (B) a second component consisting of a glycol ether; and
 - (C) a third component consisting of at least one of N-formyl morpholine, N,N-dimethyl propionamide, 3-methoxy-N,N-dimethyl propanamide, and triethyl phosphate.
2. The solvent of claim 1 in which the sulfoxide is DMSO.
3. The solvent of claim 1 in which the glycol ether is ethylene glycol monobutyl ether.
4. The solvent of claim 1 in which the first component is DMSO and the second component is ethylene glycol monobutyl ether.
5. The solvent of any of the preceding claims consisting essentially of, based on the weight of the solvent, from 50 to 90 wt% of the first component, from 9 to 40 wt% of the second component, and from 1 to 30 wt% of the third component.
6. The solvent of claim 5 in which the third component is N-formyl morpholine.
7. The solvent of claim 5 in which the third component is N,N-dimethyl propionamide.
8. The solvent of claim 5 in which the third component is 3-methoxy-N,N-dimethyl propanamide.
9. The solvent of claim 5 in which the third component is triethyl phosphate.
10. A process for cleaning or stripping the surface of a substrate, the process comprising the step of contacting the substrate with a solvent consisting essentially of:
 - (A) a first component consisting of a sulfoxide;
 - (B) a second component consisting of a glycol ether; and
 - (C) a third component consisting of at least one of N-formyl morpholine, N,N-dimethyl propionamide, 3-methoxy-N,N-dimethyl propanamide, and triethyl phosphate.

11. The process of claim 10 in which the substrate is an electronic part and the surface contains a contaminant or metal ions.

12. The process of claim 11 in which the contaminant is a poly(amic acid) residue or a polyimide residue.

13. The process of claim 10 in which the substrate is an electronic part and surface contains a photoresist.

14. The process of claim 10 in which the first component is DMSO.

15. The process of claim 10 in which the second component is ethylene glycol monobutyl ether.

16. The process of claim 10 in which the first component is DMSO and the second component is ethylene glycol monobutyl ether.

INTERNATIONAL SEARCH REPORT

International application No.

PCT/CN2016/100460

A. CLASSIFICATION OF SUBJECT MATTER

G03F 7/42(2006.01)i

According to International Patent Classification (IPC) or to both national classification and IPC

B. FIELDS SEARCHED

Minimum documentation searched (classification system followed by classification symbols)

G03F7/-

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practicable, search terms used)

cnabs,cnki,cntxt,ven:sulfoxide? or dmsol(glycol w ether?) or (ethylene w glycol w monobutyl w ether?), (formyl w morpholine?) or (dimethyl w propionamide?) or (triethyl w phosphate?),strip+

C. DOCUMENTS CONSIDERED TO BE RELEVANT

Category*	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
X	CN 104597728 A (SAMSUNG DISPLAY CO LTDET AL.) 06 May 2015 (2015-05-06) see claims 1-3,5,7-16	1-16
X	CN 101866118 A (BASF CORP) 20 October 2010 (2010-10-20) see claims 1,10,12	1-16
X	CN 103424999 A (DONGWOO FINE CHEM CO LTD) 04 December 2013 (2013-12-04) see claims 1,13-16,28-31	1-16
X	KR 20140087758 A (DONGWOO FINE CHEM CO LTD) 09 July 2014 (2014-07-09) see claims 1,3,5-7	1-16



Further documents are listed in the continuation of Box C.



See patent family annex.

* Special categories of cited documents:

"A" document defining the general state of the art which is not considered to be of particular relevance

"E" earlier application or patent but published on or after the international filing date

"L" document which may throw doubts on priority claim(s) or which is cited to establish the publication date of another citation or other special reason (as specified)

"O" document referring to an oral disclosure, use, exhibition or other means

"P" document published prior to the international filing date but later than the priority date claimed

"T" later document published after the international filing date or priority date and not in conflict with the application but cited to understand the principle or theory underlying the invention

"X" document of particular relevance; the claimed invention cannot be considered novel or cannot be considered to involve an inventive step when the document is taken alone

"Y" document of particular relevance; the claimed invention cannot be considered to involve an inventive step when the document is combined with one or more other such documents, such combination being obvious to a person skilled in the art

"&" document member of the same patent family

Date of the actual completion of the international search

01 June 2017

Date of mailing of the international search report

15 June 2017

Name and mailing address of the ISA/CN

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INTERNATIONAL SEARCH REPORT
Information on patent family members

International application No.

PCT/CN2016/100460

Patent document cited in search report			Publication date (day/month/year)	Patent family member(s)			Publication date (day/month/year)
CN	104597728	A	06 May 2015	KR	20150049674	A	08 May 2015
CN	101866118	A	20 October 2010	WO	2010118916	A1	21 October 2010
				TW	201039074	A	01 November 2010
CN	103424999	A	04 December 2013	None			
KR	20140087758	A	09 July 2014	None			